



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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TECHNOLOGY CENTER 2800  
Group Art Unit: 2827

In re the Application of: **AKAMATSU, et al**

Serial No.: **09/392,722**

Examiner: **D. E. GRAYBILL**

Filed: **September 9, 1999**

P.T.O. Confirmation No.: 1679

**FOR: INTEGRATED ELECTRONIC DEVICE HAVING FLIP-CHIP CONNECTION  
WITH CIRCUIT BOARD AND FABRICATION METHOD THEREOF**

**SUPPLEMENTAL AMENDMENT AFTER FINAL REJECTION**

Commissioner for Patents  
Washington, D.C. 20231

March 10, 2003

Sir:

In further reply to the Amendment After Final Rejection filed January 8, 2003, please amend  
the above-identified application as follows:

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**IN THE SPECIFICATION:**

**Please amend the specification as follows:**

**Please replace the paragraph beginning at page 13, line 17, with the following rewritten  
paragraph:**

Referring to FIGS. 6A-6F, processing steps for fabrication of an integrated electronic device having electric connection made of In-Ga liquid metal between a semiconductor chip and a circuit board are described. Ga-rosin mixture was prepared before fabrication of the liquid In-Ga electric connection, for which Ga was mixed with a flux vehicle at mixing ratio of 9 to 1 in weight. After the Ga